

RELIABILITY REPORT  
FOR  
MAX207CAG+  
PLASTIC ENCAPSULATED DEVICES

September 22, 2009

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

<b>Approved by</b>
Ken Wendel
Quality Assurance
Director, Reliability Engineering

## Conclusion

The MAX207CAG+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX200-MAX211/MAX213 transceivers are designed for RS-232 and V.28 communication interfaces where  $\pm 12V$  supplies are not available. On-board charge pumps convert the +5V input to the  $\pm 10V$  needed for RS-232 output levels. The MAX201 and MAX209 operate from +5V and +12V, and contain a +12V to -12V charge-pump voltage converter. The MAX200-MAX211/MAX213 drivers and receivers meet all EIA/TIA-232E and CCITT V.28 specifications at a data rate of 20kbps. The drivers maintain the  $\pm 5V$  EIA/TIA-232E output signal levels at data rates in excess of 120kbps when loaded in accordance with the EIA/TIA-232E specification. The 5 $\mu$ W shutdown mode of the MAX200, MAX205, MAX206, and MAX211 conserves energy in battery powered systems. The MAX213 has an active-low shutdown and an active-high receiver enable control. Two receivers of the MAX213 are active, allowing ring indicator (RI) to be monitored easily using only 75 $\mu$ W power. The MAX211 and MAX213 are available in a 28-pin wide small-outline (SO) package and a 28-pin shrink small-outline (SSOP) package, which occupies only 40% of the area of the SO. The MAX207 is now available in a 24-pin SO package and a 24-pin SSOP. The MAX203 and MAX205 use no external components, and are recommended for applications with limited circuit board space.

**II. Manufacturing Information**

A. Description/Function:	+5V, RS-232 Transceivers with 0.1 $\mu$ F External Capacitors
B. Process:	M6
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines
F. Date of Initial Production:	Pre 1997

**III. Packaging Information**

A. Package Type:	24-pin SSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0701-0683
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	125°C/W
K. Single Layer Theta Jc:	26°C/W

**IV. Die Information**

A. Dimensions:	138 X 155 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/1.0%Si
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

**V. Quality Assurance Information**

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

**VI. Reliability Evaluation**

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 240 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 4.5 \times 10^{-9}$$

$\lambda = 4.5 \text{ F.I.T. (60\% confidence level @ 25°C)}$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the M6 Process results in a FIT Rate of 0.22 @ 25C and 3.73 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PS29 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX207CAG+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	240	0
<b>Moisture Testing</b> (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data